48 1 1 OE

47∐ 1A1

46 1 1A2

45 GND

44 | 1A3

43 🛛 1A4

42 V<sub>CC</sub>

41 1 1A5

40 1 1A6

39 | GND

38 L 1A7

37 🛮 1A8

36 2A1

35 2A2

34 GND

33 2A3

32 2A4 31 V<sub>CC</sub>

30 2A5

29 II 2A6

28 GND

27 D 2A7

26 2A8

25 20E

SCBS084B – D3712, JANUARY 1991 – REVISED DECEMBER 1992

SN54ABT16245 . . . WD PACKAGE

SN74ABT16245...DGG OR DL PACKAGE

(TOP VIEW)

1DIR L

1B1 **1** 2

1B2 🛮

GND 4

1B3 🛮 5

1B4 🛮 6

V<sub>CC</sub> 47

1B5 🛮 8

1B6 **∐** 9

GND | 10

1B7 | 11

1B8 📙 12

2B1 🛮 13

2B2 | 14

GND 15

2B3 16

2B4 🛮 17

V<sub>CC</sub> **↓** 18

2B5 📙 19

2B6 **∏** 20

GND 1 21

2B7 🛮 22

2B8 | 23

24

2DIR 🛮

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB ™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Packaged in Plastic 300-mil Shrink Small-Outline and Thin Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings

#### description

The 'ABT16245 is a 16-bit (dual-octal) noninverting 3-state transceiver designed for synchronous two-way communication between data buses. The control function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data

transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16245 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16245 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74ABT16245 is characterized for operation from  $-40^{\circ}$ C to 85°C.

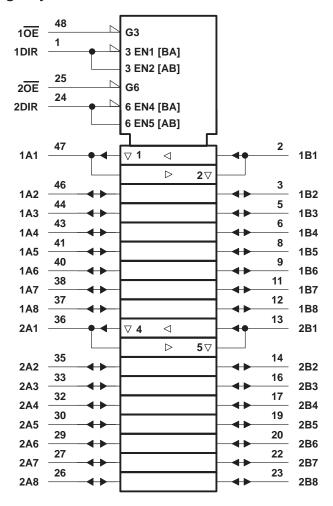
## FUNCTION TABLE (each 8-bit section)

INP	UTS	OPERATION			
ŌĒ	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	X	Isolation			

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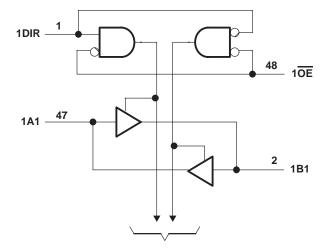
TEXAS INSTRUMENTS

#### logic symbol†

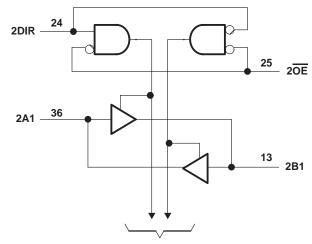


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)



To Seven Other Channels



To Seven Other Channels

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub> –0.5 V to	7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	7 V
Voltage range applied to any output in the high state or power-off state, V <sub>O</sub> −0.5 V to 5.	.5 V
Current into any output in the low state, I <sub>O</sub> : SN54ABT16245	mΑ
SN74ABT16245 128	mΑ
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	mΑ
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	mΑ
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air): DGG package	8 W
DL package	5 W
Storage temperature range –65°C to 150	0°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



#### recommended operating conditions (see Note 2)

			SN54AB	T16245	SN74AB	T16245	UNIT
			MIN	MAX	MIN	MAX	UNIT
V <sub>CC</sub> Supply voltage				5.5	4.5	5.5	V
VIH High-level input voltage					2		V
V <sub>IL</sub>	V <sub>IL</sub> Low-level input voltage					0.8	V
VI	V <sub>I</sub> Input voltage				0	VCC	V
IOH	IOH High-level output current					-32	mA
IOL	OL Low-level output current					64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS			T <sub>A</sub> = 25°C			SN54ABT16245		SN74ABT16245		UNIT	
PARAMETER	IEST	TEST CONDITIONS			TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII	
VIK	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V		
	V <sub>CC</sub> = 4.5 V,	$I_{OH} = -3 \text{ m/s}$	4	2.5			2.5		2.5			
V	V <sub>C</sub> C = 5 V,	$I_{OH} = -3 \text{ m/s}$	4	3			3		3		$\Box$ $\lor$	
VOH	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -24 \text{ m}$	nA	2			2				V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -32 \text{ m}$	nA	2‡					2			
Voi	$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 48 mA				0.55		0.55			V	
VOL	$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 64 mA				0.55‡				0.55	ı v	
1.	V <sub>CC</sub> = 5.5 V,		Control inputs			±1		±1		±1	μА	
Ч	$V_{I} = V_{CC} \text{ or GND}$		A or B ports			±100		±100		±100	μΑ	
I <sub>OZH</sub> §	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V				10¶		10		10¶	μΑ	
I <sub>OZL</sub> §	$V_{CC} = 5.5 \text{ V}, \qquad V_{O} = 0.5 \text{ V}$					-10¶		-10		-10¶	μΑ	
l <sub>off</sub>	$V_{CC} = 0$ ,	V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V				±100				±100	μΑ	
ICEX	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 \text{ V}$	V <sub>O</sub> = 5.5 V Outputs high			50		50		50	μΑ	
IO#	$V_{CC} = 5.5 \text{ V},$	$CC = 5.5 \text{ V}, \qquad V_O = 2.5 \text{ V}$		-50	-100	-180	-50	-180	-50	-180	mA	
			Outputs high			2		2		2		
lcc	$V_{CC} = 5.5 \text{ V},$ $I_{CC} = 0,$	A or B ports	Outputs low			32		32		32	mA	
icc	$V_I = V_{CC}$ or GND	A of B ports	Outputs disabled			2		2		2	IIIA	
	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	Data innuta	Outputs enabled			1		1.5		1		
ΔICC		Other inputs at	Data inputs	Outputs disabled			0.05		1		0.05	mA
	VCC 01 014B	Control inputs				1.5		1.5		1.5		
C <sub>i</sub>	$V_{ } = 2.5 \text{ V or } 0.5 \text{ V}$	$V_I = 2.5 \text{ V or } 0.5 \text{ V}$ Control inputs			3						pF	
C <sub>io</sub>	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$ A or I		A or B ports		8.5			·			pF	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.



<sup>‡</sup> On products compliant to MIL-STD-883, Class B, this parameter does not apply.

<sup>§</sup> The parameters IOZH and IOZL include the input leakage current.

This data sheet limit may vary among suppliers.

<sup>#</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

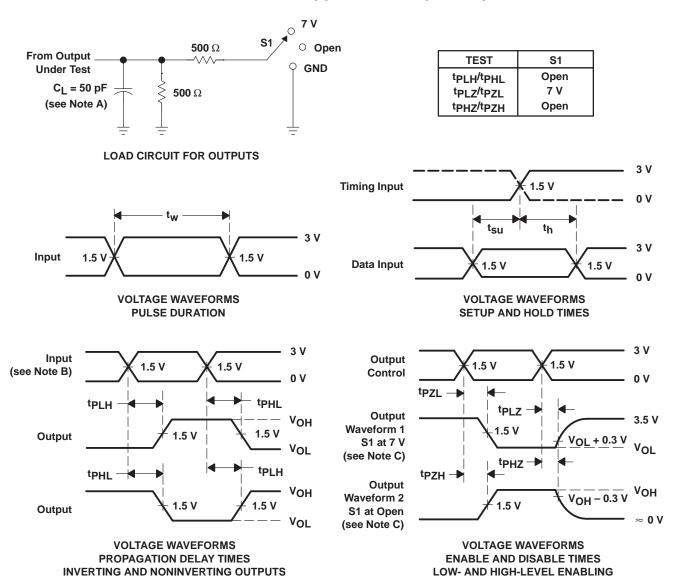
### SN54ABT16245, SN74ABT16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS084B - D3712, JANUARY 1991 - REVISED DECEMBER 1992

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT16245		SN74ABT16245		UNIT
	(INPOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	B or A	1	2.2	3.4	0.5	4	1	3.9	
t <sub>PHL</sub>	AUID	BUIA	1	2.1	3.8	0.5	4.6	1	4.5	ns
<sup>t</sup> PZH	OE	B or A	1	3.1	4.4	0.8	5.5	1	5.4	ns
tpZL	OE .	BUIA	1	3	6.1	0.9	7.3	1	7.2	115
t <sub>PHZ</sub>	OE	P.or A	1.3	3.5	4.7	1.3	6.3	1.3	5.5	no
t <sub>PLZ</sub>	]	B or A	1.4	3.2	4.7	1.4	5.3	1.4	5.2	ns

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 2.5$  ns.  $t_f \leq 2.5$  ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





ti.com 30-Mar-2005

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ABT16245DGGR	OBSOLETE	TSSOP	DGG	48	TBD	Call TI	Call TI
SN74ABT16245DL	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI
SN74ABT16245DLR	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### DL (R-PDSO-G\*\*)

#### **48 PINS SHOWN**

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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